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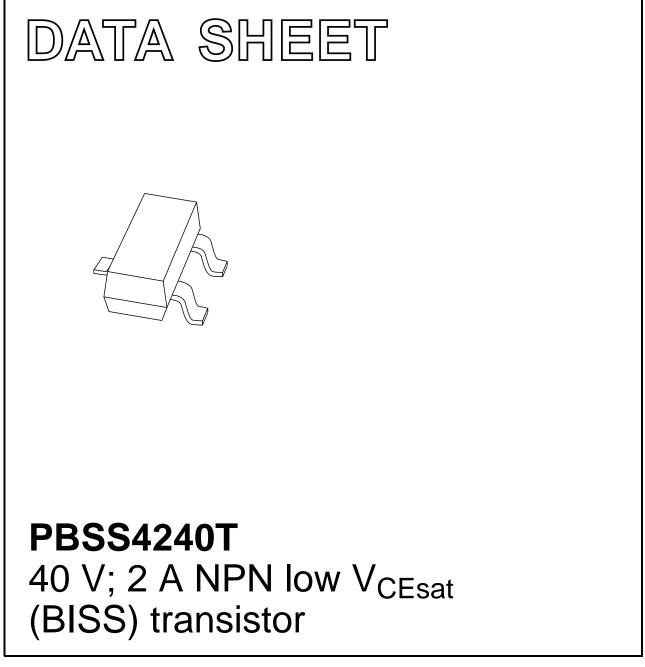
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Kind regards,

Team Nexperia

### DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 2001 Jul 13 2004 Jan 09



### Product data sheet

PBSS4240T

# 40 V; 2 A NPN low V<sub>CEsat</sub> (BISS) transistor

### FEATURES

- Low collector-emitter saturation voltage
- High current capability
- Improved device reliability due to reduced heat generation
- Replacement for SOT89/SOT223 standard packaged transistors.

#### **APPLICATIONS**

- Supply line switching circuits
- Battery management applications
- DC/DC converter applications
- Strobe flash units
- Heavy duty battery powered equipment (motor and lamp drivers).

### DESCRIPTION

NPN low  $V_{CEsat}$  transistor in a SOT23 plastic package. PNP complement: PBSS5240T.

#### MARKING

TYPE NUMBER	MARKING CODE <sup>(1)</sup>
PBSS4240T	ZE*

#### Note

- 1. \* = p: Made in Hong Kong.
  - \* = t: Made in Malaysia.
    - \* = W: Made in China.

### **ORDERING INFORMATION**

ТҮРЕ	PACKAGE		
NUMBER	NAME DESCRIPTION VERS		VERSION
PBSS4240T	<ul> <li>plastic surface mounted package; 3 leads</li> </ul>		SOT23

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	40	V
I <sub>CM</sub>	peak collector current	3	А
R <sub>CEsat</sub>	equivalent on-resistance	<200	mΩ

### PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector

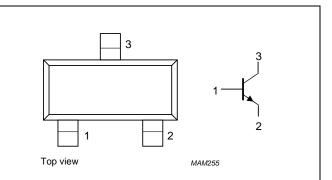


Fig.1 Simplified outline (SOT23) and symbol.

### 40 V; 2 A NPN low V<sub>CEsat</sub> (BISS) transistor

### PBSS4240T

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	-	40	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	40	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	5	V
I <sub>C</sub>	collector current (DC)		_	2	А
I <sub>CM</sub>	peak collector current		_	3	А
I <sub>BM</sub>	peak base current		-	300	mA
P <sub>tot</sub>	total power dissipation	$T_{amb} \le 25 \text{ °C}; \text{ note } 1$	_	300	mW
		$T_{amb} \le 25 \text{ °C}; \text{ note } 2$	_	480	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

### Notes

- 1. Device mounted on a printed-circuit board, single sided copper, tinplated and standard footprint.
- 2. Device mounted on a printed-circuit board, single sided copper, tinplated and mounting pad for collector 1 cm<sup>2</sup>.

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to	in free air; note 1	417	K/W
	ambient	in free air; note 2	260	K/W

### Notes

- 1. Device mounted on a printed-circuit board, single sided copper, tinplated and standard footprint.
- 2. Device mounted on a printed-circuit board, single sided copper, tinplated and mounting pad for collector 1 cm<sup>2</sup>.

# 40 V; 2 A NPN low $V_{CEsat}$ (BISS) transistor

### PBSS4240T

### CHARACTERISTICS

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	I <sub>E</sub> = 0; V <sub>CB</sub> = 30 V	-	-	100	nA
		I <sub>E</sub> = 0; V <sub>CB</sub> = 30 V; T <sub>j</sub> = 150 °C	-	-	50	μA
I <sub>EBO</sub>	emitter-base cut-off current	$I_{C} = 0; V_{EB} = 4 V$	-	_	100	nA
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 100 mA; V <sub>CE</sub> = 2 V	350	470	_	
		I <sub>C</sub> = 500 mA; V <sub>CE</sub> = 2 V	300	450	_	
		I <sub>C</sub> = 1 A; V <sub>CE</sub> = 2 V	300	420	_	
		$I_{C} = 2 \text{ A}; V_{CE} = 2 \text{ V}$	150	250	_	
V <sub>CEsat</sub>	collector-emitter saturation	I <sub>C</sub> = 100 mA; I <sub>B</sub> = 1 mA	-	45	70	mV
	voltage	I <sub>C</sub> = 500 mA; I <sub>B</sub> = 50 mA	-	70	100	mV
		I <sub>C</sub> = 750 mA; I <sub>B</sub> = 15 mA	-	120	180	mV
		$I_{C} = 1 \text{ A}; I_{B} = 50 \text{ mA}; \text{ note } 1$	-	130	180	mV
		$I_{C} = 2 \text{ A}; I_{B} = 200 \text{ mA}; \text{ note } 1$	-	240	320	mV
R <sub>CEsat</sub>	equivalent on-resistance	$I_{C} = 500 \text{ mA}; I_{B} = 50 \text{ mA}; \text{ note } 1$	-	140	<200	mΩ
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = 2 A; I <sub>B</sub> = 200 mA; note 1	-	-	1.1	V
V <sub>BEon</sub>	base-emitter turn on voltage	I <sub>C</sub> = 100 mA; V <sub>CE</sub> = 2 V	-	-	0.75	V
Cc	collector capacitance	$I_E = I_e = 0; V_{CB} = 10 V; f = 1 MHz$	-	15	20	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 100 mA; V <sub>CE</sub> = 10 V; f = 100 MHz	100	230	_	MHz

### Note

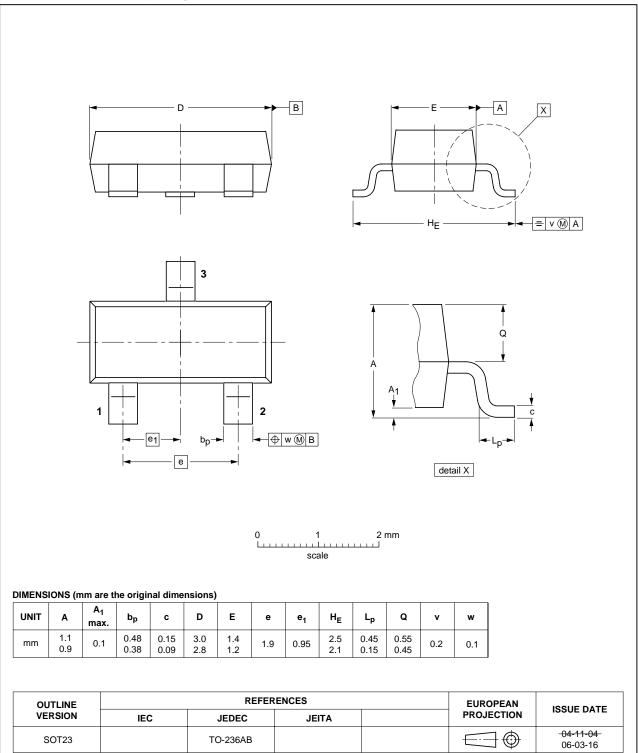
1. Pulse test:  $t_p \leq 300~\mu s; ~\delta \leq 0.02.$ 

SOT23

## 40 V; 2 A NPN low V<sub>CEsat</sub> (BISS) transistor

### PACKAGE OUTLINE





### PBSS4240T

### 40 V; 2 A NPN low V<sub>CEsat</sub> (BISS) transistor

### PBSS4240T

### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

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#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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